

In the Claims:

1-36. (Cancelled)

37. (New) A package for an integrated circuit die comprising:

a die pad having a first die pad surface, a second die pad surface opposite the first die pad surface, and a peripheral die pad side surface extending between the first and second die pad surfaces;

a plurality of contacts, each of the contacts having a first end facing the die pad, a second end opposite the first end, a first contact surface, a second contact surface opposite the first contact surface, and opposing contact side surfaces extending between the first and second ends and the first and second contact surfaces;

an integrated circuit die disposed on the first die pad surface;

at least one conductor electrically connected to and extending between the die and the first contact surface of a respective one of the contacts; and

a package body formed of an encapsulant material which covers the die, the second contact surface of each of the contacts being exposed within the package body;

the die pad side surface including a means for vertically locking the die pad to the package body, with the contact side surfaces and the first end of each of the contacts including a means for vertically locking the contacts to the package body.

38. (New) The package of Claim 37 wherein the second die pad surface of the die pad is exposed within the package body.

39. (New) The package of Claim 37 wherein the package body defines exterior side surfaces, and the second end of each of the contacts is exposed within a respective one of the side surfaces of the package body.

40. (New) The package of Claim 37 wherein the first die pad surface and the first contact surface of each of the contacts extend in generally co-planar relation to each other.

41. (New) The package of Claim 40 wherein the second die pad surface and the second contact surface of each of the contacts extend in generally co-planar relation to each other.

42. (New) The package of Claim 37 wherein the second die pad surface is fully covered by the package body.

43. (New) A package for an integrated circuit die comprising:

a die pad having a first die pad surface, a second die pad surface opposite the first die pad surface, and a peripheral die pad side surface extending between the first and second die pad surfaces;

a plurality of contacts, each of the contacts having a first end facing the die pad, a second end opposite the first end, a first contact surface, a second contact surface opposite the first contact surface, and opposing contact side surfaces extending between the first and second ends and the first and second contact surfaces;

an integrated circuit die disposed on the first die pad surface;

at least one conductor electrically connected to and extending between the die and the first contact surface of a respective one of the contacts; and

a package body formed of an encapsulant material which covers the die, the second contact surface of each of the contacts being exposed within the package body;

the die pad side surface including a means for vertically locking the die pad to the package body, with at least the first end of each of the contacts including a means for vertically locking the contacts to the package body.

44. (New) The package of Claim 43 wherein the second die pad surface of the die pad is exposed within the package body.

45. (New) The package of Claim 43 wherein the package body defines exterior side surfaces, and the second end of each of the contacts is exposed within a respective one of the side surfaces of the package body.

46. (New) The package of Claim 43 wherein the first die pad surface and the first contact surface of each of the contacts extend in generally co-planar relation to each other.

47. (New) The package of Claim 46 wherein the second die pad surface and the second contact surface of each of the contacts extend in generally co-planar relation to each other.

48. (New) The package of Claim 43 wherein the second die pad surface is fully covered by the package body.

49. (New) A package for an integrated circuit die comprising:

a die pad having a first die pad surface, a second die pad surface opposite the first die pad surface, and a peripheral die pad side surface extending between the first and second die pad surfaces;

a plurality of contacts, each of the contacts having a first end facing the die pad, a second end opposite the first end, a first contact surface, a second contact surface opposite the first contact surface, and opposing contact side surfaces extending between the first and second ends and the first and second contact surfaces;

an integrated circuit die disposed on the first die pad surface;

means for electrically connecting the die to at least one of the contacts; and

a package body formed of an encapsulant material which covers the die, the second contact surface of each of the contacts being exposed within the package body;

the die pad side surface including a means for vertically locking the die pad to the package body, with the contact side surfaces and the first end of each of the contacts including a means for vertically locking the contacts to the package body.

50. (New) The package of Claim 49 wherein the second die pad surface of the die pad is exposed within the package body.

51. (New) The package of Claim 49 wherein the package body defines exterior side surfaces, and the second end of each of the contacts is exposed within a respective one of the side surfaces of the package body.

52. (New) The package of Claim 49 wherein the first die pad surface and the first contact surface of each of the contacts extend in generally co-planar relation to each other.

53. (New) The package of Claim 52 wherein the second die pad surface and the second contact surface of each of the contacts extend in generally co-planar relation to each other.

54. (New) The package of Claim 49 wherein the second die pad surface is fully covered by the package body.

55. (New) A semiconductor package comprising:

means for mounting an integrated circuit die;

means for providing electrical contact between the semiconductor package and means external to the semiconductor package;

an integrated circuit die mounted on a first surface of the mounting means;

means for electrically connecting the die to the contact means;

means for at least partially encapsulating the mounting means, the contact means, the connecting means and the die;

means for locking the mounting means to the encapsulating means; and

means for locking the contact means to the encapsulating means.